

SKM200GB125DN

Features

- ▶ High short circuit capability, self limiting short circuit current
- ▶ IGBT CHIP (Highly rugged SPT+ design)
- ▶ VCE(sat) with positive temperature coefficient
- ▶ Ultra Low Loss, High ruggedness
- ▶ Free wheeling diodes with fast and soft reverse recovery

Applications

- ▶ AC motor control
- ▶ Inverter and power supplies
- ▶ Motion/servo control
- ▶ Photovoltaic/Fuel cell



Absolute Maximum Ratings T_c=25°C, unless otherwise specified

Symbol	Conditions	Values	Units	
IGBT				
V _{CES}	T _j =25°C	1200	V	
I _C	T _j =150°C	T _{case} =25°C	200	V
		T _{case} =85°C	160	V
I _{CRM}	I _{CRM} =2×I _{Cnom}	300	A	
V _{GES}		±20	V	
t _{psc}	V _{CC} =600V; V _{GE} ≤ 20V; V _{CES} <1200V	T _j =125°C	10	μs
Inverse Diode				
I _F	T _j =150°C	T _{case} =25°C	200	A
		T _{case} =80°C	130	A
I _{FRM}	I _{FRM} =2×I _{Fnom}	300	A	
I _{FSM}	t _p =10ms; sin.	T _j =150°C	1440	A
Module				
I _t (RMS)		500	A	
T _{vj}		-40...+150	°C	
T _{stg}		-40...+150	°C	
V _{isol}	AC, 1min.	4000	V	

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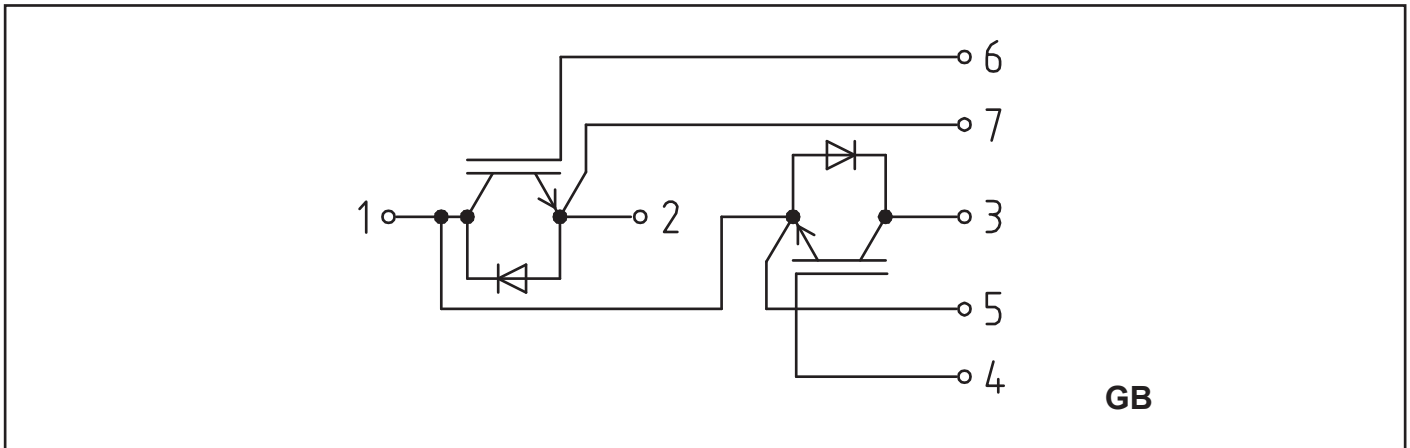
Characteristics $T_c=25^\circ\text{C}$, unless otherwise specified

Symbol	Conditions	min.	typ.	max.	Units	
IGBT						
$V_{GE(th)}$	$V_{GE} = V_{CE}, I_C = 6\text{mA}$	4.5	5.5	6.5	V	
I_{CES}	$V_{GE} = 0\text{V}, V_{CE} = V_{CES}$	$T_j=25^\circ\text{C}$		0.15	0.45	mA
		$T_j=125^\circ\text{C}$				mA
V_{CE0}		$T_j=25^\circ\text{C}$		1.5	1.75	V
		$T_j=125^\circ\text{C}$				V
r_{CE}	$V_{GE} = 15\text{V}$	$T_j=25^\circ\text{C}$		12	14	$\text{m}\Omega$
		$T_j=125^\circ\text{C}$				$\text{m}\Omega$
$V_{CE(sat)}$	$I_{Cnom} = 150\text{A}, V_{GE}=15\text{V}$			3.3	3.85	V
C_{ies}	$V_{CE} = 25\text{V}, V_{GE} = 0\text{V}$	$f = 1\text{MHz}$		10	13	nF
C_{oes}				1.5	2	nF
C_{res}				0.8	1.2	nF
Q_G	$V_{GE} = 0\text{--}+20\text{V}$			1300		nC
R_{Gint}		$T_j=^\circ\text{C}$		2.5		Ω
$t_{d(on)}$	$R_{Gon} = 4\Omega$	$V_{CC} = 600\text{V}$ $I_C = 150\text{A}$		75		ns
t_r				36		ns
E_{on}		$T_j=125^\circ\text{C}$		14		mJ
$t_{d(off)}$	$R_{Goff} = 4\Omega$	$V_{GE} = \pm 15\text{V}$		420		ns
t_f				25		ns
E_{off}						mJ
$R_{th(j-c)}$	per IGBT			0.09		K/W
Inverse Diode						
$V_F = V_{EC}$	$I_{Fnom} = 150\text{A}; V_{GE}=0\text{V}$	$T_j=25^\circ\text{Cchiplev.}$		2	2.5	V
		$T_j=125^\circ\text{Cchiplev.}$		1.8		V
V_{F0}		$T_j=25^\circ\text{C}$		1.1	1.2	V
		$T_j=125^\circ\text{C}$				V
r_F		$T_j=25^\circ\text{C}$		6	8.7	$\text{m}\Omega$
		$T_j=125^\circ\text{C}$				$\text{m}\Omega$
I_{RRM}	$I_F=150\text{A}$ $di/dt=5500\text{A}/\mu\text{s}$ $V_{GE} = 0\text{V}; V_{CC}=600\text{V}$	$T_j=125^\circ\text{C}$		230		A
Q_{rr}				24		μC
E_{rr}						
$R_{th(j-c)D}$	per diode			0.25		K/W
Module						
L_{CE}				15	20	nH
$R_{CC'+EE'}$	res.terminal-chip	$T_{case}=25^\circ\text{C}$		0.35		$\text{m}\Omega$
		$T_{case}=125^\circ\text{C}$		0.5		$\text{m}\Omega$
$R_{th(c-s)}$	per module			0.038		K/W
M_s	to heat sink M6		3	5		Nm
M_t	to heat sink M6		2.5	5		Nm
W				325		g

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Symbol	Conditions	Values	Units
Z_{th(j-c)I}			
R _j	i = 1	60	mk/W
R _j	i = 2	23	mk/W
R _j	i = 3	5.9	mk/W
R _j	i = 4	1.1	mk/W
tau _i	i = 1	0.0744	s
tau _i	i = 2	0.0087	s
tau _i	i = 3	0.002	s
tau _i	i = 4	0.0015	s
Z_{th(j-c)D}			
R _j	i = 1	160	mk/W
R _j	i = 2	67	mk/W
R _j	i = 3	20	mk/W
R _j	i = 4	3	mk/W
tau _i	i = 1	0.0536	s
tau _i	i = 2	0.0034	s
tau _i	i = 3	0.077	s
tau _i	i = 4	0.0003	s

Circuit Diagram



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Package Outline

